

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Canceled)
2. (Amended) A printed wiring board comprising:
 - A. at least two conductive circuit layers separated by nonconductive material;
 - B. at least one recess in said nonconductive material defined by a nonconductive surface intersecting at least two of said conductive circuit layers, said at least one recess having a diameter within the range of about 0.15 mm to about 6 mm;
 - C. an electrically conductive coating adhered to [on] said nonconductive surface defining said recess, said coating including electrically conductive carbon having a mean particle size no greater than about 1 micron and a water-dispersible organic binding agent, wherein said coating is electrically conductive, thereby allowing electrical current to flow between the two conductive circuit layers such that the electrically conductive coating can accept [and accepts] electroplating to provide a surface at least substantially free of visible voids.
3. (Original) The printed wiring board of claim 2, having a resistivity between said conductive circuit layers of less than about 1000 ohms prior to electroplating.
4. (Original) The printed wiring board of claim 2, having a resistivity between said conductive circuit layers of less than about 600 ohms, prior to electroplating.
5. (Original) The printed wiring board of claim 2, having a resistivity between said conductive circuit layers of less than about 400 ohms, prior to electroplating.

6. (Original) The printed wiring board of claim 2, having a resistivity between said conductive circuit layers of less than about 250 ohms, prior to electroplating.

7. (Original) The printed wiring board of claim 2, having a resistivity between said conductive circuit layers of less than about 80 ohms, prior to electroplating.

8. (Original) The printed wiring board of claim 2, having a resistivity of less than about 60 ohms between said conductive circuit layers, prior to electroplating.

9. (Original) The printed wiring board of claim 2, having a resistivity between said conductive circuit layers of less than about 30 ohms, prior to electroplating.

10. (Original) The printed wiring board of claim 2, having a resistivity between said conductive circuit layers of less than about 10 ohms, prior to electroplating.

11. (Original) The printed wiring board of claim 2, having a resistivity between said conductive circuit layers of less than about 2 ohms, prior to electroplating.

12. (Original) The printed wiring board of claim 2, including a multiplicity of said conductive through holes including said coating.

13. (Original) The printed wiring board of claim 2, wherein said coating is not greater than about 12 microns thick.

14. (Original) The printed wiring board of claim 2, wherein said coating is not greater than about 7 microns thick.

15. (Original) The printed wiring board of claim 2, wherein said coating is not greater than about three microns thick.

16. (Original) The printed wiring board of claim 2, wherein said coating is not greater than about one micron thick.

17. (Original) The printed wiring board of claim 2, wherein said coating is free of lumpiness.

18. (Original) The printed wiring board of claim 2, wherein said water-dispersible organic binding agent is selected from the group consisting of monosaccharides, polysaccharides, and combinations thereof.

19. (Original) The printed wiring board of claim 2, wherein said electrically conductive carbon comprises graphite.

20. (Canceled)

21. (Previously presented) The printed wiring board of claim 2, further comprising an electroplated layer deposited on at least a portion of said electrically conductive coating.

22. (Original) The printed wiring board of claim 21, further comprising a solder layer deposited on at least a portion of said electroplated layer.